

Features

The plastic package carries Underwriters Laboratory
 Flammability Classification 94V-0
 Construction utilizes void-free molded plastic technique
 Low reverse leakage
 High forward surge current capability
 High temperature soldering guaranteed
 260°C/10 seconds at terminals

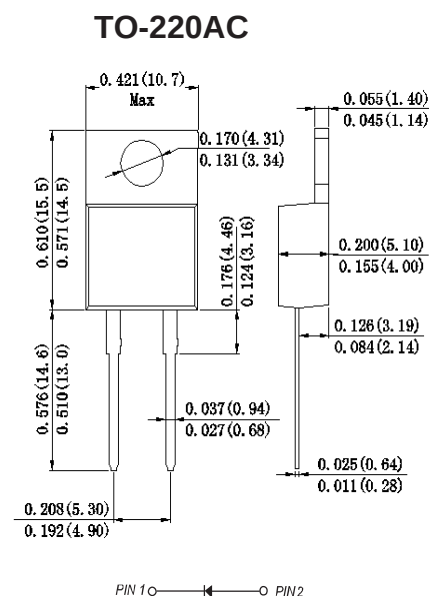
Mechanical Data

Case : Molded plastic body

Terminals : Solder plated, solderable per MIL-STD-750,Method 2026

Polarity : Polarity symbol marking on body

Mounting Position : Any



Dimensions in inches and (millimeters)

Maximum Ratings And Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified. Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

Parameter	SYMBOLS	MUR1660	UNITS
Maximum repetitive peak reverse voltage	V_{RRM}	600	V
Maximum RMS voltage	V_{RMS}	420	V
Maximum DC blocking voltage	V_{DC}	600	V
Maximum average forward rectified current at $T_c=110^\circ\text{C}$	$I_{(AV)}$	15.0	A
Peak forward surge current, 8.3ms single half sine-wave superimposed on rated load	I_{FSM}	200	A
Maximum instantaneous forward voltage per diode at 16.0A	V_F	2.2	V
Maximum DC reverse current $T_A=25^\circ\text{C}$ at rated DC blocking voltage $T_A=125^\circ\text{C}$	I_R	10 500	μA
Maximum reverse recovery time	T_{rr}	60	ns
Typical thermal resistance	R_{qJC}	35.0	$^\circ\text{C/W}$
Operating junction temperature range	T_J	-55 to +150	$^\circ\text{C}$
Storage temperature range	T_{STG}	-55 to +150	$^\circ\text{C}$

Note: 1. Reverse recovery time test condition: $I_F=0.5\text{A}$ $I_R=1.0\text{A}$ $t_{rr}=0.25\text{A}$

Ratings And Characteristic Curves

FIG. 1- DERATING CURVE OUTPUT RECTIFIED CURRENT

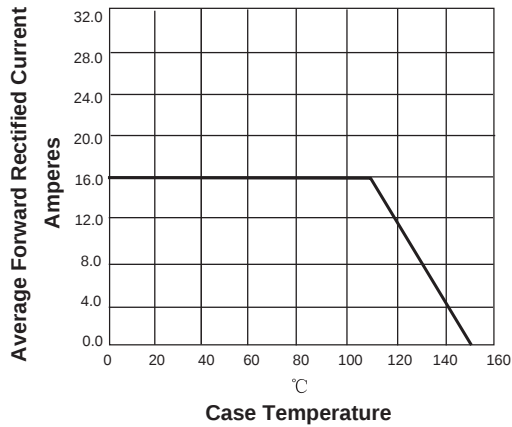


FIG. 2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT PER LEG

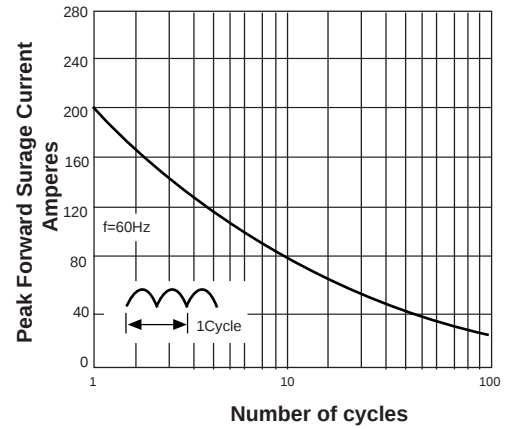


FIG. 3-TYPICAL FORWARD VOLTAGE CHARACTERISTICS

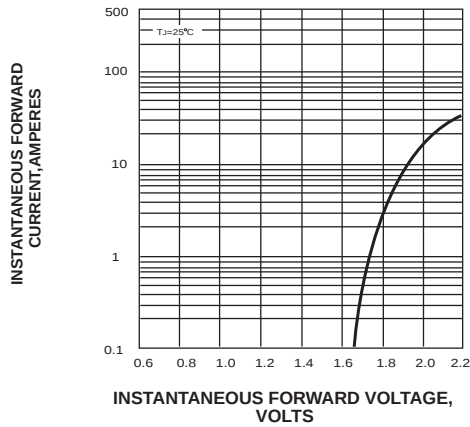
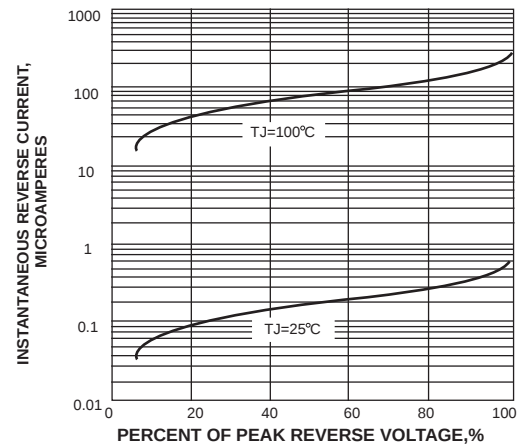
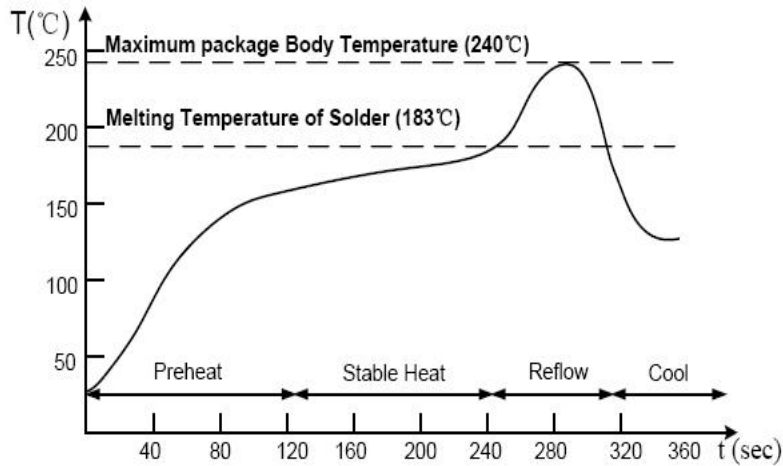


FIG. 4-TYPICAL REVERSE LEAKAGE CHARACTERISTICS



Suggested Soldering Temperature Profile



Note

Recommended reflow methods: IR, vapor phase oven, hot air oven, wave solder.
 The device can be exposed to a maximum temperature of 265°C for 10 seconds.
 Devices can be cleaned using standard industry methods and solvents.
 If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

Package Information

Tube Package

Package	Tube (mm)	Q'TY/Tube (Kpcs)	Box Size (mm)	QTY/Box (Kpcs)	Carton Size (mm)	Q'TY/Carton (Kpcs)
TO	525*31.9*6.4	0.05	545*150*45	1.0	575*245*170	5.0

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